



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20190118000.0
Datasheet for ISO7720, ISO7721
Information Only**

Date: January 22, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO7720DWR	null
ISO7720FDWR	null
ISO7721DW	null
ISO7721FDW	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190118000.0	PCN Date:	January 22, 2019
Title:	Datasheet for ISO7720, ISO7721		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



ISO7720, ISO7721

SLLSEP3D – NOVEMBER 2016 – REVISED JANUARY 2019

Changes from Revision C (July 2018) to Revision D	Page
• Made editorial and cosmetic changes throughout the document.....	1
• Changed From: "Isolation Barrier Life: >40 Years" To: ">100-Year Projected Lifetime at 1.5 kV _{RMS} Working Voltage" in Features	1
• Added "Up to 5000 V _{RMS} Isolation Rating" in Features	1
• Added "Up to 12.8 kV Surge Capability" in Features	1
• Added "±8 kV IEC 61000-4-2 Contact Discharge Protection across Isolation Barrier" in Features	1
• Added "Automotive Version Available: ISO772x-Q1" in Features	1
• Deleted "Certification Planned" statement throughout the document.....	1
• Updated Applications list.....	1
• Updated Simplified Schematic to show two isolation capacitors in series per channel instead of a single isolation capacitor.....	1
• Added "Contact discharge per IEC 61000-4-2" specification of ±8000 V in ESD Ratings table.....	5
• Changed 'Signaling' rate to 'Data' rate and added table note to <i>Data rate</i> specification in Recommended Operating Conditions table.....	5
• Changed V _{IORM} Value for DW-16 and DWV-8 packages From: "1414 V _{PK} " To: "2121 V _{PK} " in Insulation Specifications table.....	7
• Changed V _{IOWM} Values for DW-16 and DWV-8 packages From: "1000 V _{RMS} " and "1414 V _{DC} " To: "1500 V _{RMS} " and "2121 V _{DC} " in Insulation Specifications table.....	7
• Added 'see Figure 26 ' to TEST CONDITIONS of V _{IOWM} specification.....	7
• Changed V _{IOTM} TEST CONDITIONS for 100% production test From: "V _{TEST} = V _{IOTM} " To: "V _{TEST} = 1.2 x V _{IOTM} " in Insulation Specifications table.....	7
• Changed V _{IOSM} TEST CONDITIONS From: "Test method per IEC 60065" To: "Test method per IEC 62368-1" in Insulation Specifications table.....	7
• Changed q _{pd} TEST CONDITIONS for method b1 test From: "V _{ini} = V _{IOTM} " To: "V _{ini} = 1.2 x V _{IOTM} " in Insulation Specifications table.....	7
• Updated certification information in Safety-Related Certifications table.....	8
• Added Insulation Lifetime sub-section under Application Curve section.....	24
• Added 'How to use isolation to improve ESD, EFT and Surge immunity in industrial systems' application report to Documentation Support section.....	27

The datasheet number will be changing.

Device Family	Change From:	Change To:
ISO7720, ISO7721	SLLSEP3C	SLLSEP3D

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/ISO7720>

Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
ISO7720D	ISO7720FD	ISO7721D	ISO7721FD
ISO7720DR	ISO7720FDR	ISO7721DR	ISO7721FDR
ISO7720DW	ISO7720FDW	ISO7721DW	ISO7721FDW
ISO7720DWR	ISO7720FDWR	ISO7721DWR	ISO7721FDWR
ISO7720DWV	ISO7720FDWV	ISO7721DWV	ISO7721FDWV
ISO7720DWVR	ISO7720FDWVR	ISO7721DWVR	ISO7721FDWVR

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com